



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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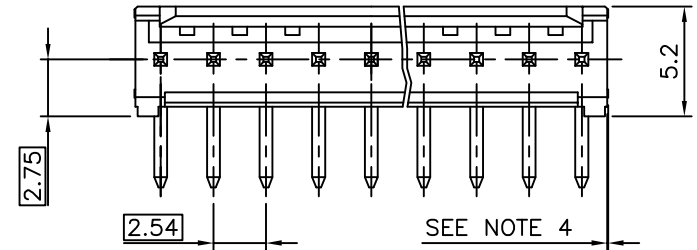
PRODUCT NUMBER
76382-YXXLF

PLATING

RoHS COMPATIBLE, SEE NOTE 7
NUMBER OF POSITIONS : 02 TO 36

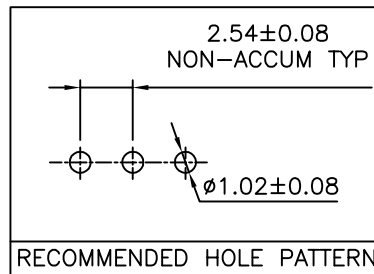
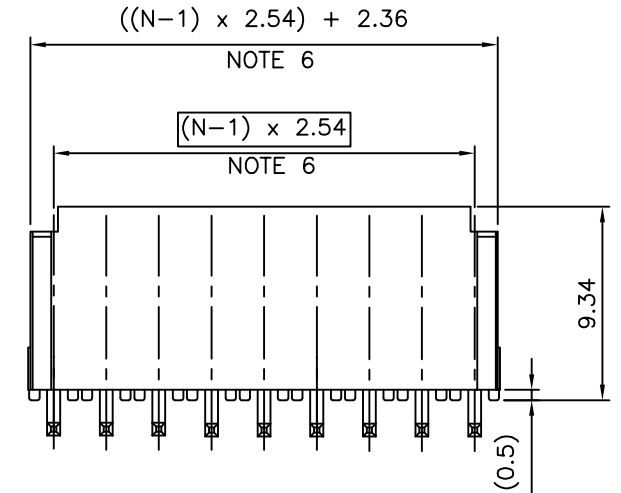
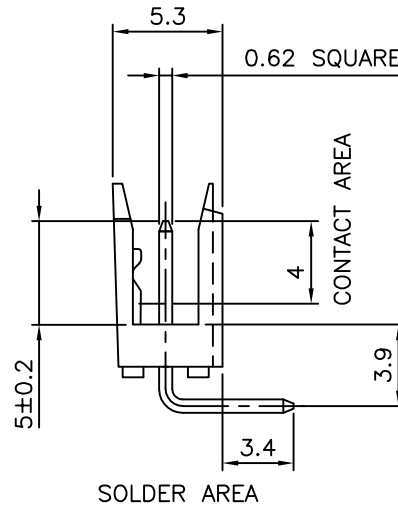
3=0.76µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
1.27µm Ni MIN UNDERPLATING

TOP VIEW



NOTES:

1. BODY MATERIAL: POLYESTER 30% GLASSFILLED COLOR BLUE, FLAME RETARDANT PER UL-94 V0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE.
3. 15N MIN PIN RETENTION IN EITHER DIRECTION
4. 0.6 MAX PROTRUSION PERMITTED AT 4 PLACES
5. PACKAGING :
- POLYBAGS FROM 02 TO 06 POSITIONS
- TUBE FROM 07 TO 36 POSITIONS
6. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO
245°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - c - LABELING:
- MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
SEE NOTE		ISO 1302		ISO 406 ISO 1101				DUBOX	
ltr		ecn no		date				title	
S	F-21810	AMA	15.06.19	angles		.X ±0.3		SHR. HEADER	
				linear		.XX ±0.15		RA SR TMT	
L	F05-0117	LMU	05.01.27			.XXX ±0.05		scale 5:1	
M	F05-0244	JCO	05.09.06	dr		D.LE 01.01.24		dwg no	
N	F06-0228	LMU	06.07.11	engr		J.M.C 01.01.24		sheet 1 of 1 size	
P	F08-0147	YOV	08.04.14	chr		J.M.C 01.01.24		76382 A3	
R	B-19285	AMA	14.11.03	appd		J.F.N 01.01.24		type	
sheet		revision						CUSTOMER Drawing	
index		sheet							